

LNPT[™] THERMOCOMP[™] COMPOUND OF008E

OF-1008 EM

REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP OF008E compound is based on linear Polyphenylene Sulfide (PPS) resin containing 40% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyphenylene Sulfide, Linear (PPS, Linear)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break	178	MPa	ASTM D638
Tensile Strain, break	1.7	%	ASTM D638
Flexural Stress	248	MPa	ASTM D790
Flexural modulus	14260	MPa	ASTM D790
Tensile Stress, break	160	MPa	ISO 527
Tensile Strain, break	1.2	%	ISO 527
Flexural Stress	190	MPa	ISO 178
Flexural Modulus	13400	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	587	J/m	ASTM D4812
Izod Impact, notched, 23°C	101	J/m	ASTM D256
Izod Impact, unnotched 80°10*4 +23°C	21	kJ/m ²	ISO 180/1U
Izod Impact, notched 80°10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	261	°C	ASTM D648
CTE, -40°C to 40°C, flow	2.6E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80°10*4 sp=64mm	268	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.68	g/cm ³	ASTM D792

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.8	%	ASTM D955
Wear Factor Washer	240	10 ⁻¹⁰ in ⁴ 5-min/ft-lb-hr	ASTM D3702 Modified: Manual
Dynamic COF	0.66	-	ASTM D3702 Modified: Manual
Static COF	0.87	-	ASTM D3702 Modified: Manual
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Melt Temperature	315 – 320	°C	
Front - Zone 3 Temperature	330 – 345	°C	
Middle - Zone 2 Temperature	320 – 330	°C	
Rear - Zone 1 Temperature	305 – 315	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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